

ABSTRACT

An active microelectronic element such as a semiconductor chip or wafer is bonded to an interconnect element having substantially the same coefficient of thermal expansion as the active element using small, rigid bonds, desirably made by a solid-phase bonding technique, which accommodate numerous closely-spaced interconnections. The assembly is provided with terminals movable with respect to the active element and interconnect element. The interconnect element desirably provides low-impedance conductive paths interconnecting active electronic devices within the active element.

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